



Material Content Data Sheet



Sales Product Name		BTT6100-2EKA		Issued		19. April 2016		
MA#		MA001503314						
Package		PG-DSO-14-40		Weight*		149.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.998	1.34	1.34	13391	13391
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		117	
	non noble metal	zinc	7440-66-6	0.070	0.05		466	
	non noble metal	iron	7439-89-6	1.392	0.93		9328	
wire	non noble metal	copper	7440-50-8	56.512	37.88	38.87	378760	388671
	non noble metal	copper	7440-50-8	0.522	0.35	0.35	3501	3501
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1144
encapsulation	plastics	epoxy resin	-	7.852	5.26		52625	
	inorganic material	silicondioxide	60676-86-0	77.322	51.83	57.20	518241	572010
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8218	8218
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9501	9501
glue	plastics	epoxy resin	-	0.123	0.08		824	
	noble metal	silver	7440-22-4	0.580	0.39	0.47	3884	4708
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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